

SKiiP 22NAB12T4V2



MiniSKiiP® 2

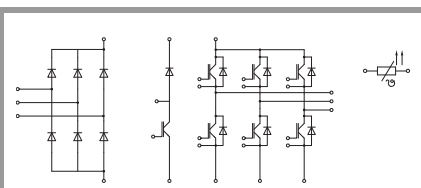
SKiiP 22NAB12T4V2

Features*

- Trench 4 IGBTs
- Robust and soft freewheeling diodes in CAL technology
- Highly reliable spring contacts for electrical connections
- UL recognised: File no. E63532

Remarks

- Max. case temperature limited to $T_C=125^\circ\text{C}$
- Product reliability results valid for $T_j \leq 150^\circ\text{C}$ (recommended $T_{j,op} = -40 \dots +150^\circ\text{C}$)
- Please refer to MiniSKiiP "Technical Explanations" and "Mounting Instructions" for further information
- No functional isolation between temperature sensor and "-DC/V" and "-DC/W"



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Absolute Maximum Ratings				
Symbol	Conditions		Values	Unit
Inverter - IGBT				
V_{CES}	$T_j = 25^\circ\text{C}$		1200	V
I_C	$\lambda_{paste}=0.8 \text{ W/(mK)}$	$T_s = 25^\circ\text{C}$	27	A
		$T_j = 175^\circ\text{C}$	22	A
I_C	$\lambda_{paste}=2.5 \text{ W/(mK)}$	$T_s = 25^\circ\text{C}$	30	A
		$T_j = 175^\circ\text{C}$	24	A
I_{Cnom}			15	A
I_{CRM}	$I_{CRM} = 3 \times I_{Cnom}$		45	A
V_{GES}			-20 ... 20	V
t_{psc}	$V_{CC} = 800 \text{ V}$	$T_j = 150^\circ\text{C}$	10	μs
	$V_{GE} \leq 15 \text{ V}$			
	$V_{CES} \leq 1200 \text{ V}$			
T_j			-40 ... 175	$^\circ\text{C}$
Chopper - IGBT				
V_{CES}	$T_j = 25^\circ\text{C}$		1200	V
I_C	$\lambda_{paste}=0.8 \text{ W/(mK)}$	$T_s = 25^\circ\text{C}$	27	A
		$T_j = 175^\circ\text{C}$	22	A
I_C	$\lambda_{paste}=2.5 \text{ W/(mK)}$	$T_s = 25^\circ\text{C}$	30	A
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	$V_{GE} \leq 15 \text{ V}$			
	$V_{CES} \leq 1200 \text{ V}$			
T_j			-40 ... 175	$^\circ\text{C}$
Inverse - Diode				
V_{RRM}	$T_j = 25^\circ\text{C}$		1200	V
I_F	$\lambda_{paste}=0.8 \text{ W/(mK)}$	$T_s = 25^\circ\text{C}$	22	A
		$T_j = 175^\circ\text{C}$	18	A
I_F	$\lambda_{paste}=2.5 \text{ W/(mK)}$	$T_s = 25^\circ\text{C}$	24	A
		$T_j = 175^\circ\text{C}$	20	A
I_{Fnom}			15	A
I_{FRM}	$I_{FRM} = 2 \times I_{Fnom}$		30	A
I_{FSM}	$t_p = 10 \text{ ms, sin } 180^\circ, T_j = 150^\circ\text{C}$		65	A
T_j			-40 ... 175	$^\circ\text{C}$
Freewheeling - Diode				
V_{RRM}	$T_j = 25^\circ\text{C}$		1200	V
I_F	$\lambda_{paste}=0.8 \text{ W/(mK)}$	$T_s = 25^\circ\text{C}$	22	A
		$T_j = 175^\circ\text{C}$	18	A
I_F	$\lambda_{paste}=2.5 \text{ W/(mK)}$	$T_s = 25^\circ\text{C}$	24	A
		$T_j = 175^\circ\text{C}$	20	A
I_{Fnom}			15	A
I_{FRM}	$I_{FRM} = 2 \times I_{Fnom}$		30	A
I_{FSM}	$t_p = 10 \text{ ms, sin } 180^\circ, T_j = 150^\circ\text{C}$		65	A
T_j			-40 ... 175	$^\circ\text{C}$

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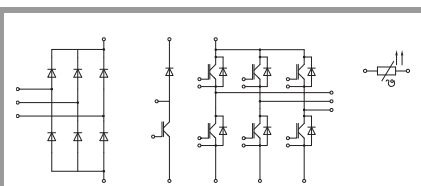
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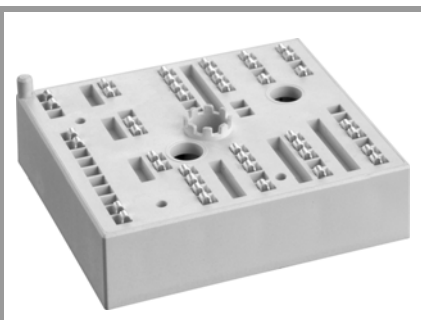
Absolute Maximum Ratings				
Symbol	Conditions		Values	Unit
Rectifier - Diode				
V_{RRM}	$T_j = 25^\circ\text{C}$		1600	V
I_F	$\lambda_{paste}=0.8 \text{ W/(mK)}$	$T_s = 25^\circ\text{C}$	37	A
		$T_j = 150^\circ\text{C}$	28	A
I_F	$\lambda_{paste}=2.5 \text{ W/(mK)}$	$T_s = 25^\circ\text{C}$	40	A
		$T_j = 150^\circ\text{C}$	31	A
I_{Fnom}			8	A
I_{FSM}	10 ms sin 180°	$T_j = 25^\circ\text{C}$	220	A
		$T_j = 150^\circ\text{C}$	200	A
I^2t	10 ms sin 180°	$T_j = 25^\circ\text{C}$	242	A ² s
		$T_j = 150^\circ\text{C}$	200	A ² s
T_j			-40 ... 150	°C
Module				
$I_{t(RMS)}$	$T_{terminal} = 80^\circ\text{C}$, 20 A per spring		18	A
T_{stg}			-40 ... 125	°C
V_{isol}	AC sinus 50 Hz, 1 min		2500	V

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
Inverter - IGBT						
$V_{CE(sat)}$	$I_C = 15 \text{ A}$ $V_{GE} = 15 \text{ V}$ chipelevel	$T_j = 25^\circ\text{C}$	1.85	2.10		V
		$T_j = 150^\circ\text{C}$	2.25	2.45		V
V_{CE0}	chipelevel	$T_j = 25^\circ\text{C}$	0.80	0.90		V
		$T_j = 150^\circ\text{C}$	0.70	0.80		V
r_{CE}	$V_{GE} = 15 \text{ V}$ chipelevel	$T_j = 25^\circ\text{C}$	70	80		mΩ
		$T_j = 150^\circ\text{C}$	103	110		mΩ
$V_{GE(th)}$	$V_{GE} = V_{CE} \text{ V}$, $I_C = 0.5 \text{ mA}$		5	5.8	6.5	V
I_{CES}	$V_{GE} = 0 \text{ V}$, $V_{CE} = 1200 \text{ V}$, $T_j = 25^\circ\text{C}$				0.3	mA
C_{ies}	$V_{CE} = 25 \text{ V}$ $V_{GE} = 0 \text{ V}$	$f = 1 \text{ MHz}$	0.90			nF
C_{oes}		$f = 1 \text{ MHz}$	0.08			nF
C_{res}		$f = 1 \text{ MHz}$	0.06			nF
Q_G	$V_{GE} = -8 \text{ V} \dots +15 \text{ V}$		85			nC
R_{Gint}	$T_j = 25^\circ\text{C}$		0			Ω
$t_{d(on)}$	$V_{CC} = 600 \text{ V}$ $I_C = 15 \text{ A}$	$T_j = 150^\circ\text{C}$	5			ns
t_r		$T_j = 150^\circ\text{C}$	37			ns
E_{on}	$R_{G on} = 16 \Omega$ $R_{G off} = 16 \Omega$	$T_j = 150^\circ\text{C}$	1.5			mJ
$t_{d(off)}$		$T_j = 150^\circ\text{C}$	286			ns
t_f	$di/dt_{on} = 370 \text{ A}/\mu\text{s}$ $di/dt_{off} = 167 \text{ A}/\mu\text{s}$	$T_j = 150^\circ\text{C}$	86			ns
E_{off}	$V_{GE} = +15/-15 \text{ V}$		1.54			mJ
$R_{th(j-s)}$	per IGBT, $\lambda_{paste}=0.8 \text{ W/(mK)}$		1.4			K/W
$R_{th(j-s)}$	per IGBT, $\lambda_{paste}=2.5 \text{ W/(mK)}$		1.2			K/W



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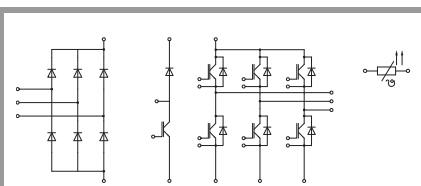
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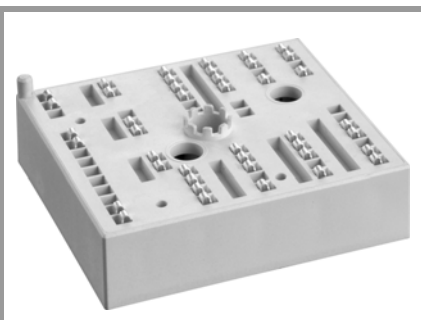
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- Please refer to MiniSKiIP "Technical Explanations" and "Mounting Instructions" for further information
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Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
Chopper - IGBT						
$V_{CE(sat)}$	$I_C = 15\text{ A}$ $V_{GE} = 15\text{ V}$ chipelevel	$T_j = 25^\circ\text{C}$		1.85	2.10	V
		$T_j = 150^\circ\text{C}$		2.25	2.45	V
V_{CE0}	chipelevel	$T_j = 25^\circ\text{C}$		0.80	0.90	V
		$T_j = 150^\circ\text{C}$		0.70	0.80	V
r_{CE}	$V_{GE} = 15\text{ V}$ chipelevel	$T_j = 25^\circ\text{C}$		70	80	m Ω
		$T_j = 150^\circ\text{C}$		103	110	m Ω
$V_{GE(th)}$	$V_{GE} = V_{CE}\text{ V}, I_C = 0.5\text{ mA}$		5	5.8	6.5	V
I_{CES}	$V_{GE} = 0\text{ V}, V_{CE} = 1200\text{ V}, T_j = 25^\circ\text{C}$				0.3	mA
Q_G	$V_{GE} = -8\text{ V} \dots +15\text{ V}$			85		nC
R_{Gint}	$T_j = 25^\circ\text{C}$			0		Ω
$t_{d(on)}$	$V_{CC} = 600\text{ V}$	$T_j = 150^\circ\text{C}$		5		ns
t_r	$I_C = 15\text{ A}$ $R_{G\ on} = 16\ \Omega$	$T_j = 150^\circ\text{C}$		37		ns
		$T_j = 150^\circ\text{C}$		1.5		mJ
E_{on}	$T_j = 150^\circ\text{C}$			1.5		mJ
$t_{d(off)}$	$di/dt_{on} = 370\text{ A}/\mu\text{s}$	$T_j = 150^\circ\text{C}$		286		ns
t_f	$di/dt_{off} = 167\text{ A}/\mu\text{s}$	$T_j = 150^\circ\text{C}$		86		ns
E_{off}	$V_{GE} = +15/-15\text{ V}$	$T_j = 150^\circ\text{C}$		1.5		mJ
		$T_j = 150^\circ\text{C}$		1.4		K/W
$R_{th(j-s)}$	per IGBT, $\lambda_{paste}=0.8\text{ W}/(\text{mK})$			1.2		K/W
$R_{th(j-s)}$	per IGBT, $\lambda_{paste}=2.5\text{ W}/(\text{mK})$			1.2		K/W
Inverse - Diode						
$V_F = V_{EC}$	$I_F = 15\text{ A}$ $V_{GE} = 0\text{ V}$ chipelevel	$T_j = 25^\circ\text{C}$		2.38	2.71	V
		$T_j = 150^\circ\text{C}$		2.44	2.77	V
V_{F0}	chipelevel	$T_j = 25^\circ\text{C}$		1.30	1.50	V
		$T_j = 150^\circ\text{C}$		0.90	1.10	V
r_F	chipelevel	$T_j = 25^\circ\text{C}$		72	81	m Ω
		$T_j = 150^\circ\text{C}$		103	111	m Ω
I_{RRM}	$I_F = 15\text{ A}$	$T_j = 150^\circ\text{C}$		11.6		A
Q_{rr}	$di/dt_{off} = 370\text{ A}/\mu\text{s}$ $V_{GE} = -15\text{ V}$	$T_j = 150^\circ\text{C}$		2.4		μC
		$T_j = 150^\circ\text{C}$		0.95		mJ
E_{rr}	$V_{CC} = 600\text{ V}$	$T_j = 150^\circ\text{C}$		0.95		mJ
$R_{th(j-s)}$	per Diode, $\lambda_{paste}=0.8\text{ W}/(\text{mK})$			2		K/W
$R_{th(j-s)}$	per Diode, $\lambda_{paste}=2.5\text{ W}/(\text{mK})$			1.7		K/W
Freewheeling - Diode						
$V_F = V_{EC}$	$I_F = 15\text{ A}$ $V_{GE} = 0\text{ V}$ chipelevel	$T_j = 25^\circ\text{C}$		2.38	2.71	V
		$T_j = 150^\circ\text{C}$		2.44	2.77	V
V_{F0}	chipelevel	$T_j = 25^\circ\text{C}$		1.30	1.50	V
		$T_j = 150^\circ\text{C}$		0.90	1.10	V
r_F	chipelevel	$T_j = 25^\circ\text{C}$		72	81	m Ω
		$T_j = 150^\circ\text{C}$		103	111	m Ω
I_{RRM}	$I_F = 15\text{ A}$	$T_j = 150^\circ\text{C}$		11.6		A
Q_{rr}	$di/dt_{off} = 370\text{ A}/\mu\text{s}$ $V_{GE} = -15\text{ V}$	$T_j = 150^\circ\text{C}$		2.4		μC
		$T_j = 150^\circ\text{C}$		0.95		mJ
E_{rr}	$V_{CC} = 600\text{ V}$	$T_j = 150^\circ\text{C}$		0.95		mJ
$R_{th(j-s)}$	per Diode, $\lambda_{paste}=0.8\text{ W}/(\text{mK})$			2		K/W
$R_{th(j-s)}$	per Diode, $\lambda_{paste}=2.5\text{ W}/(\text{mK})$			1.7		K/W

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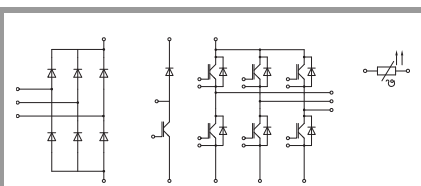
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- Please refer to MiniSKiiP "Technical Explanations" and "Mounting Instructions" for further information
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Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
Rectifier - Diode						
$V_F = V_{EC}$	$I_F = 8 \text{ A}$ $V_{GE} = 0 \text{ V}$ chipllevel	$T_j = 25^\circ\text{C}$		1.00	1.21	V
		$T_j = 125^\circ\text{C}$		0.90	1.10	V
V_{F0}	chipllevel	$T_j = 25^\circ\text{C}$		0.88	0.98	V
		$T_j = 125^\circ\text{C}$		0.73	0.83	V
r_F	chipllevel	$T_j = 25^\circ\text{C}$		15	29	m Ω
		$T_j = 125^\circ\text{C}$		21	34	m Ω
I_R	$T_j = 145^\circ\text{C}, V_{RRM}$				1.1	mA
$R_{th(j-s)}$	per Diode, $\lambda_{paste}=0.8 \text{ W/(mK)}$			1.63		K/W
$R_{th(j-s)}$	per Diode, $\lambda_{paste}=2.5 \text{ W/(mK)}$			1.4		K/W
Module						
M_s	to heat sink		2		2.5	Nm
w				55		g
L_{CE}				-		nH
Temperature Sensor						
R_{100}	$T_r = 100^\circ\text{C}$			1670 \pm 3%		Ω
$R(T)$	$R(T)=1000\Omega[1+A(T-25^\circ\text{C})+B(T-25^\circ\text{C})^2]$, $A = 7.635 \cdot 10^{-3} \text{ }^\circ\text{C}^{-1}$, $B = 1.731 \cdot 10^{-5} \text{ }^\circ\text{C}^{-2}$					



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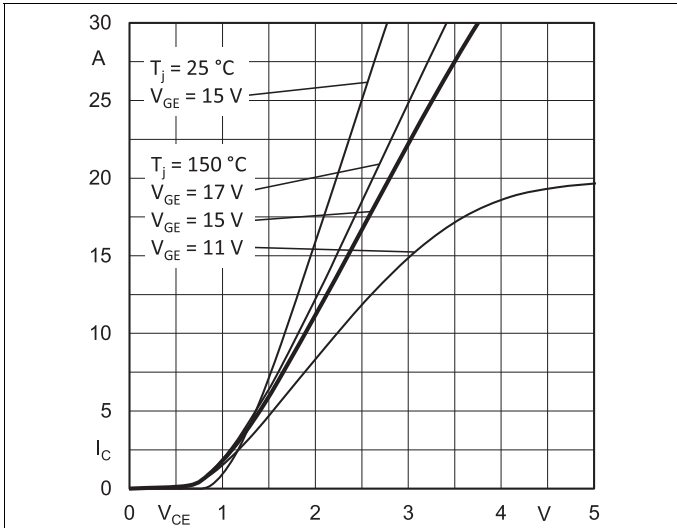


Fig. 1: Typ. output characteristic, inclusive $R_{CC'+EE'}$

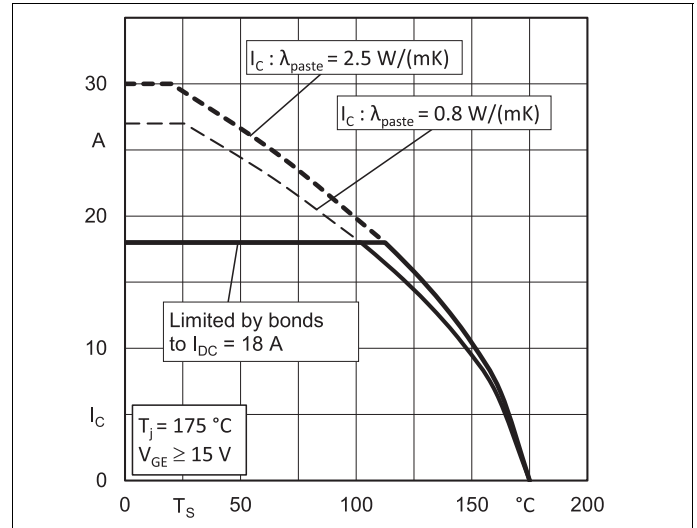


Fig. 2: Typ. rated current vs. temperature $I_C = f(T_s)$

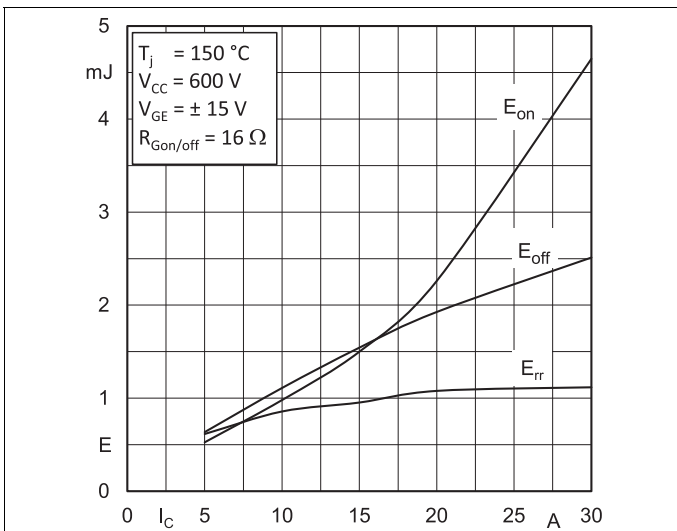


Fig. 3: Typ. turn-on /-off energy = $f(I_C)$

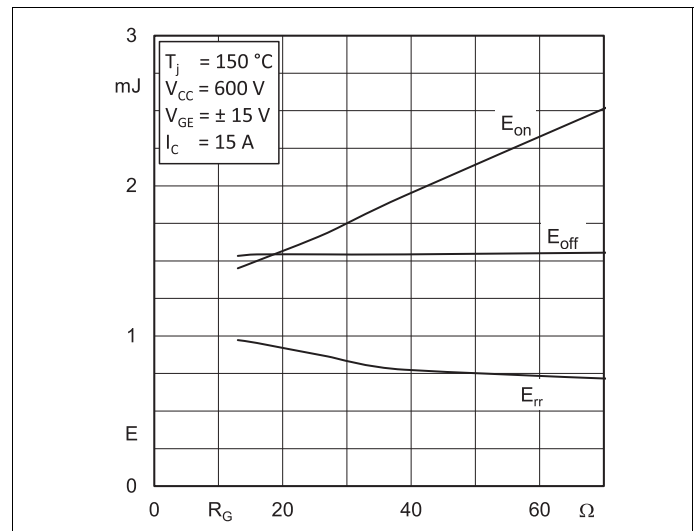


Fig. 4: Typ. turn-on /-off energy = $f(R_G)$

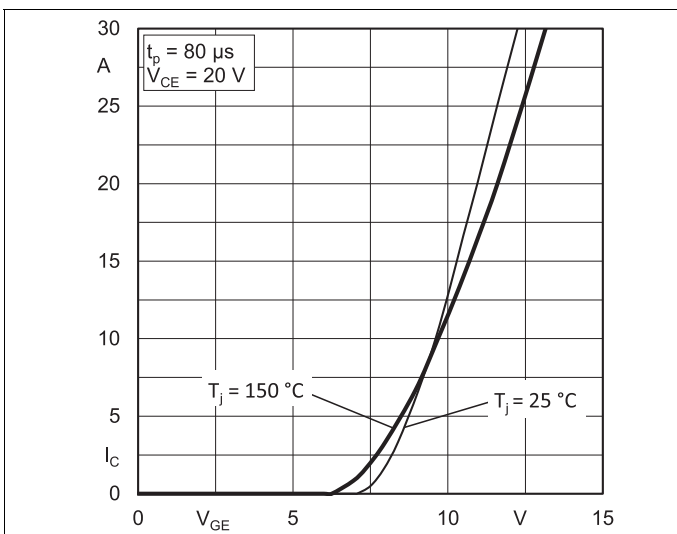


Fig. 5: Typ. transfer characteristic

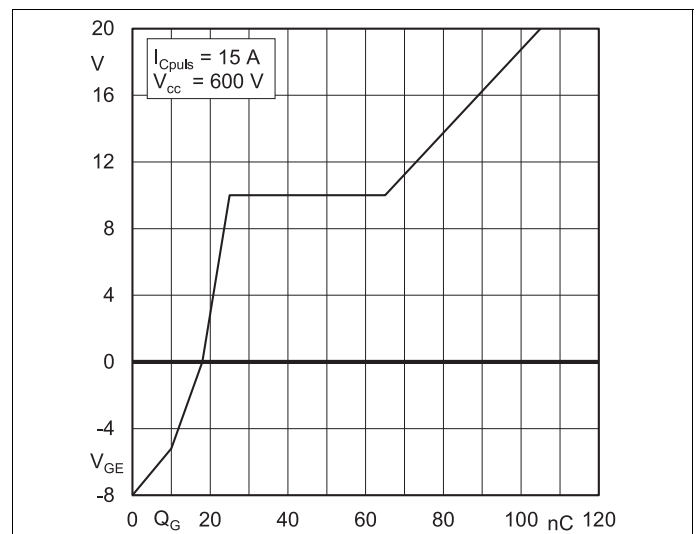


Fig. 6: Typ. gate charge characteristic

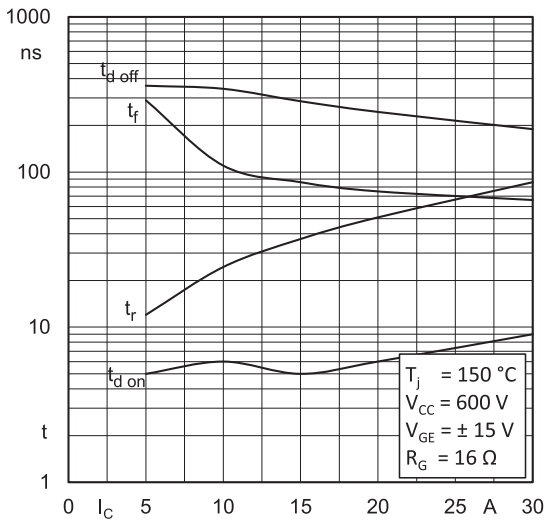


Fig. 7: Typ. switching times vs. I_C

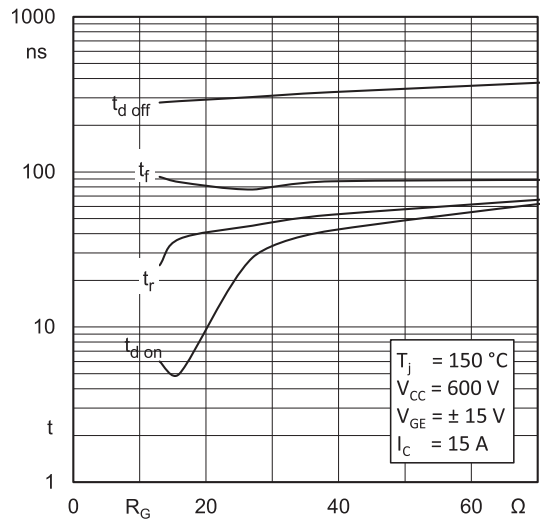


Fig. 8: Typ. switching times vs. gate resistor R_G

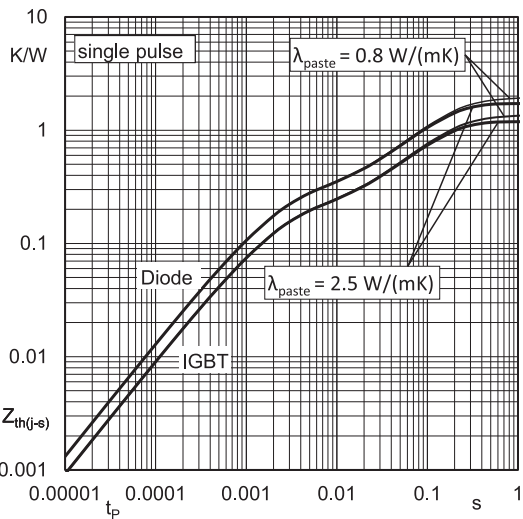


Fig. 9: Typ. transient thermal impedance

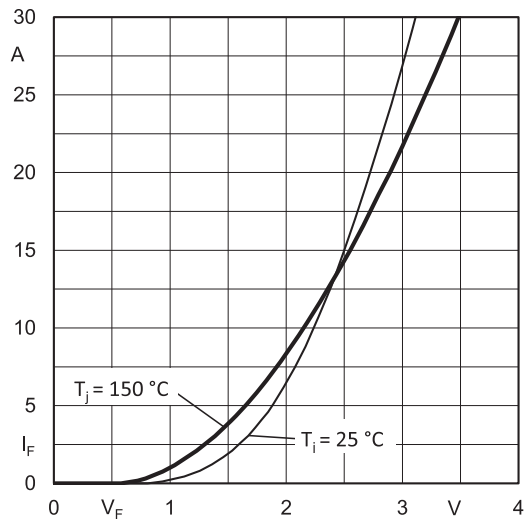


Fig. 10: Typ. CAL diode forward charact., incl. $R_{CC+EE'}$

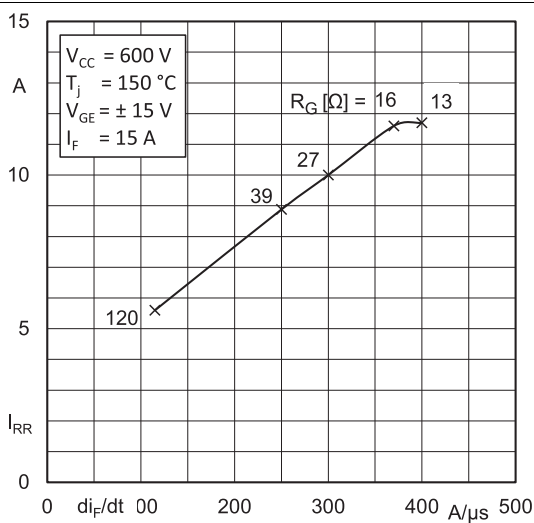


Fig. 11: Typ. CAL diode peak reverse recovery current

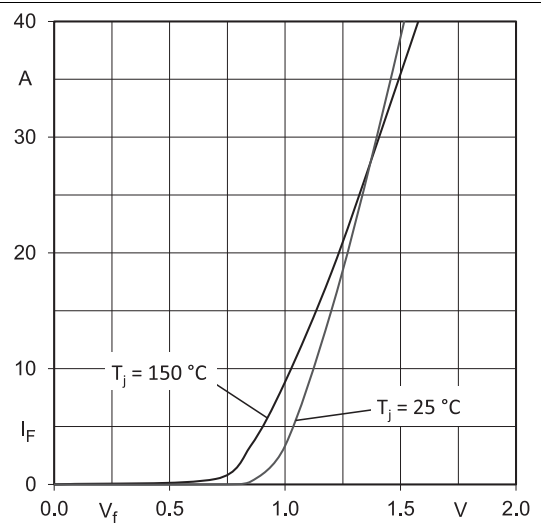
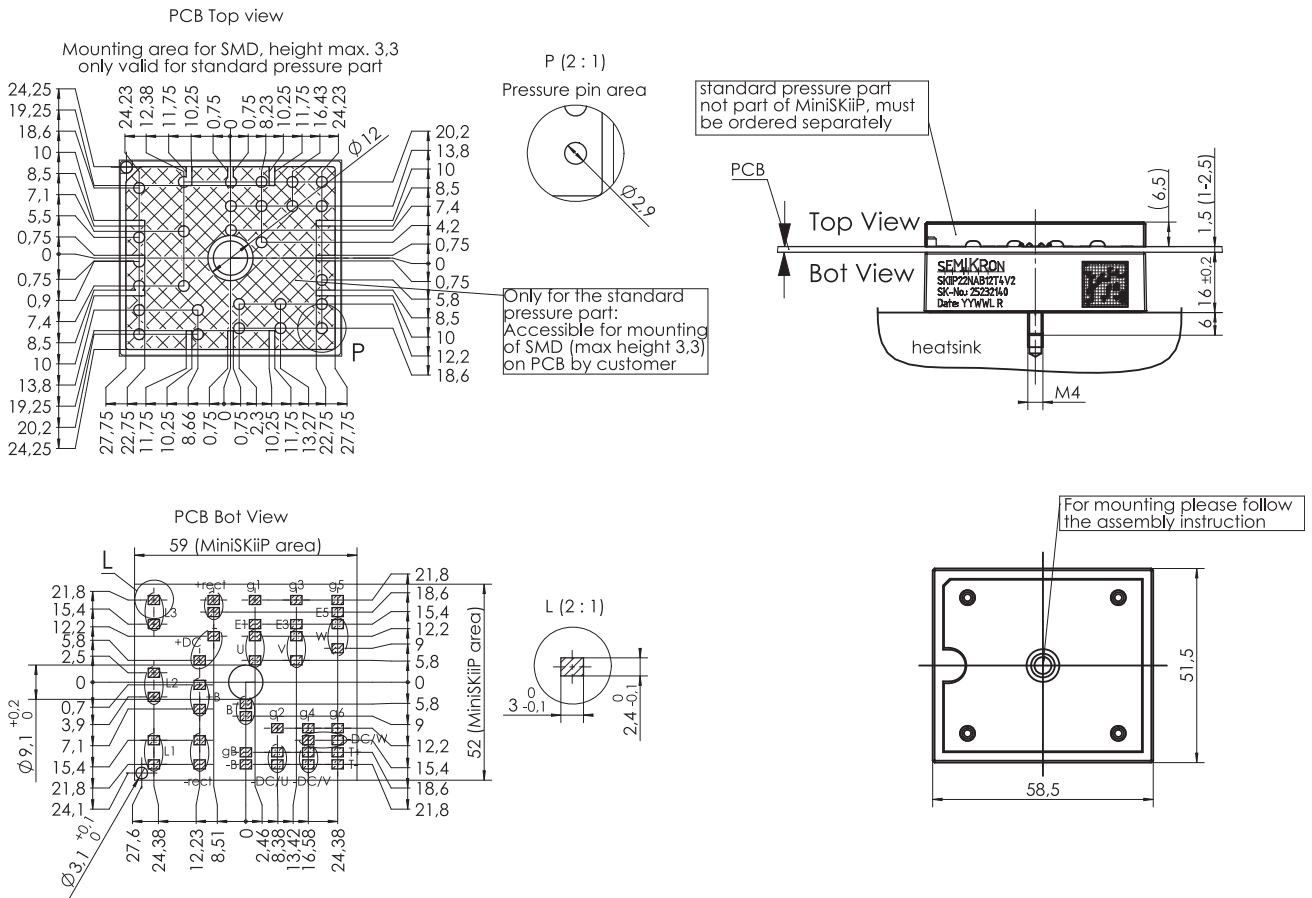
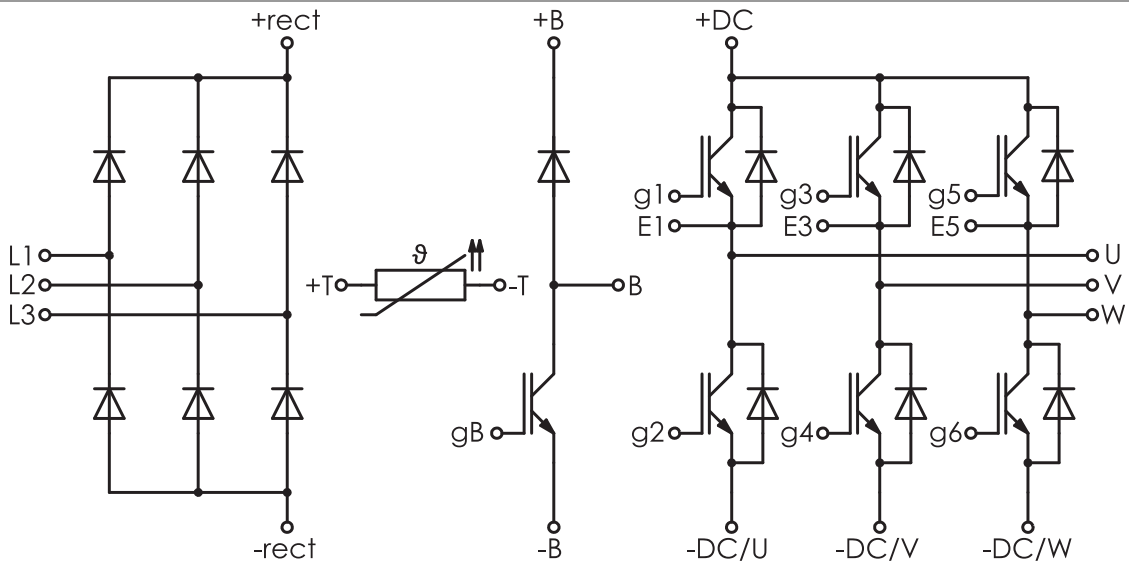


Fig. 12: Typ. input bridge forward characteristic incl. $R_{CC+EE'}$

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pinout, dimensions



pinout

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, chapter IX.

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